

# Product Change Notification

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The information below reflects a change that is being implemented.

Notice Date: 03/06/2006

Product Category: Battery Management; Infrared Devices; Linear Devices; Mixed Signal Devices; Power Management; RS232; Supervisor; Thermal Management; dsPIC; CAN Communication; Infrared Communication; LIN Communication; Serial Communication; 24xxx; 25xxx; 93xxx; PIC10xxx; PIC12xxx; PIC16xxx; PIC17xxx; PIC18xxx; PIC24xxx; rPIC; PSxxx; RFID; SDP

Notification Subject: Change #592 - ISHIZAKI SnPb & MATTE TIN PLATING QUALIFICATION

Notification Body:

Microchip Part#s Affected ( REQUIRED: List part#'s and/or product category affected)  
All Devices, All Packages

Description of Change:  
QUALIFICATION OF NEW PLATING SITE FOR SnPb & MATTE TIN PLATING

Impacts to Data Sheet:  
NONE

Reason for Change:  
ADDITIONAL CAPACITY

Estimated Change Implementation Date(s):  
APRIL 4, 2006

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)  
none

Summary of Qualification Results: (Reference Report Number if applicable):  
SnPb PLATING:  
SOLDERABILITY TEST RESULTS PER JESD22B-102D: 0/240 UNITS  
MATTE TIN PLATING:  
SOLDERABILITY TEST RESULTS PER JESD22B-102D: 0/180 UNITS  
1500 TEMP CYCLING WHISKER TEST RESULTS PER JESD201: 0/576 LEADS, 0/36 UNITS, < 45 µM TIN WHISKERS  
2000 HRS HIGH T/H WHISKER TEST RESULTS PER JESD201: 0/576LEADS, 0/36 UNITS, < 40 µM TIN WHISKERS  
3000 HRS HIGH T/H WHISKER TEST RESULTS PER JESD201: 0/288LEADS, 0/18 UNITS, < 40 µM TIN WHISKERS  
2000 HRS AMBIENT T/H WHISKER TEST RESULTS PER JESD201: 0/576LEADS, 0/36 UNITS, < 40 µM TIN WHISKERS  
3000 HRS AMBIENT T/H WHISKER TEST RESULTS PER JESD201: 0/288LEADS, 0/18 UNITS, < 40 µM TIN WHISKERS